

Appl. No. 10/064,462
Amdt. dated September 08, 2005
Reply to Office action of 06/16/2005

AMENDMENTS TO THE CLAIMS

1-13. (cancelled)

5 14. (previously presented) A method for attaching an integrated circuit (IC) package to a circuit board, the IC package having a plurality of electrical contacts, the plurality of electrical contacts being disposed on a major surface of the IC package in an arrangement having a perimeter, the method comprising:

10 positioning the IC package relative to the circuit board, such that the major surface of the IC package is adjacent to a major surface of the circuit board;
electrically connecting the IC package to the circuit board through the plurality of electrical contacts; and
15 disposing at least one strip of solder between the major surface of the IC package and the major surface of the circuit board to mechanically attach the IC package to the circuit board;
wherein the strip of solder does not provide an electrical contact between the IC package and the circuit board.

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15. (previously presented) The method of claim 14 wherein the strip of solder is disposed at a location outside of the perimeter of the plurality of electrical contacts.

25 16. (previously presented) The method of claim 15 wherein the major surface of the IC package has a rectangular shape, and the arrangement of the plurality of electrical contacts is a grid-like array.

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17. (previously presented) The method of claim 16 wherein the strip of solder is disposed along four edges of the major surface of the IC package.